DS15EA101 0.15 to 1.5 Gbps Adaptive Cable Equalizer with LOS Detection

Check for Samples: DS15EA101

FEATURES

- **Automatic Equalization of Coaxial, Twin-Ax and Twisted Pair Cables**
- **High Data Rates: 150 Mbps to 1.5+ Gbps**
- **Up to 35 dB of Boost at 750 MHz**
- **LOS Detection and Output Enable**
- **Single-Ended or Differential Input**
- **50Ω Differential Outputs**
- **Low Power Operation, 210 mW (typ) at 1.5 Gbps**
- **Industrial -40°C to +85°C Temperature**
- **Space-Saving 4 x 4 mm WQFN-16 Package**

APPLICATIONS

- **Cable Extention Applications**
- **Security Cameras**
- **Remote LCDs and LED Panels**
- **Data Recovery Equalization**

DESCRIPTION

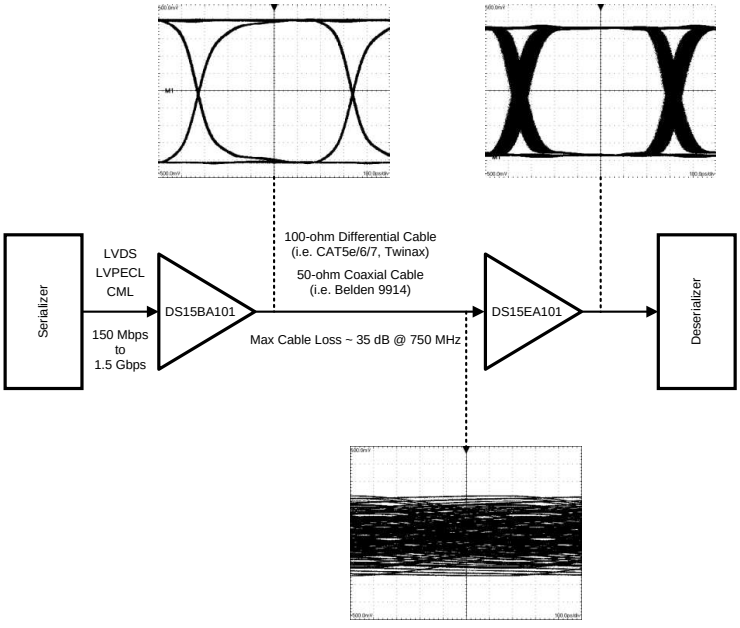
The DS15EA101 is an adaptive equalizer optimized for equalizing data transmitted over copper cables. The DS15EA101 operates over a wide range of data rates from 150 Mbps to 1.5+ Gbps and automatically adapts to equalize any cable length from zero meters to lengths that attenuate the signal by 35 dB at 750 MHz.

The DS15EA101 allows either single-ended or differential input drive. This enables equalization of coaxial cables as well as differential twin-ax and twisted pair cables.

Additional features include an LOS output and an output enable which, when tied together, disable the output when no signal is present.

The DS15EA101 is powered from a single 3.3V supply and consumes 210 mW at 1.5 Gbps. It operates over the full −40°C to +85°C industrial temperature range and is available in a space saving 4 x 4 mm WQFN-16 package which allows for high density placement of components in multi-channel applications.

Typical Application



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings(1)

Supply Voltage	−0.5V to 3.6V
Input Voltage (all inputs)	−0.3V to V_{CC}+0.3V
Storage Temperature Range	−65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (Soldering 4 Sec)	+260°C
Package Thermal Resistance θ_{JA} RGH0016A θ_{JC} RGH0016A	 +42.1°C/W +8.2°C/W
ESD Rating (HBM)	8 kV
ESD Rating (MM)	250V

(1) "Absolute Maximum Ratings" are those parameter values beyond which the life and operation of the device cannot be ensured. The stating herein of these maximums shall not be construed to imply that the device can or should be operated at or beyond these values. The table of Electrical Characteristics specifies acceptable device operating conditions.

Recommended Operating Conditions

Supply Voltage (VCC)	3.3V ±5%
Input Coupling Capacitance	1.0 µF
Loop Capacitor (Connected between CAP+ and CAP-)	1.0 µF
Operating Free Air Temperature (T_A)	-40°C to +85°C

DC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified (1) (2).

Symbol	Parameter	Conditions	Reference	Min	Typ	Max	Units
V_{CM}	Input Common Mode Voltage		IN+, IN-		1.9		V
V_{IN}	Input Voltage					(3)(4)950	mV_{P-P}
V_{OS}	Output Common Mode Voltage		OUT+, OUT-		V_{CC} – V_{OUT}/2		V
V_{OUT}	Output Voltage Swing	50Ω load, differential			750		mV_{P-P}
V_{LOS}	LOS Output Voltage	Valid signal not present	LOS	2.6			V
		Valid signal present				0.4	V
$V_{IN(EN)}$	$\overline{EN}$ Input Voltage	Min to disable outputs	$\overline{EN}$	3.0			V
		Max to enable outputs				0.8	V
I_{CC}	Supply Current	(5)			63	77	mA

(1) Current flow into device pins is defined as positive. Current flow out of device pins is defined as negative. All voltages are stated referenced to 0 volts.
(2) Typical values are stated for V_{CC} = +3.3V and T_A = +25°C.
(3) Specification is ensured by characterization.
(4) The maximum input voltage amplitude assumes a DC-balanced signal.
(5) Supply current depends on the amount of cable being equalized. The current is highest for short cable and decreases as the cable length is increased.

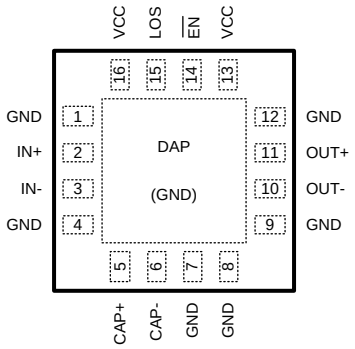
AC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified (1).

Symbol	Parameter	Conditions	Reference	Min	Typ	Max	Units
BR_{IN}	Input Data Rate		IN+, IN-	150		1500	Mbps
t_{TRJ}	Total Residual Jitter @ BER-12 (2)	1.5 Gbps 25m CAT5e (Belden 1700A), (1)			0.25		UI
		1.0 Gbps 50m CAT5e (Belden 1700A), (1)			0.25		UI
		0.5 Gbps 100m CAT5e (Belden 1700A), (1)			0.25		UI
		1.5 Gbps 50m CAT7 (Siemon Tera), (1)			0.25		UI
		1.5 Gbps 75m CAT7 (Siemon Tera), (1)			0.30		UI
		1.0 Gbps 100m CAT7 (Siemon Tera), (1)			0.40		UI
		1.5 Gbps 200m Belden 9914, (1)			0.25		UI
tTLH	Transition Time from Low to High	20% – 80%, (3)	OUT+, OUT-		100	220	ps
tTHL	Transition Time from High to Low	20% – 80%, (3)			100	220	ps
R_{OUT}	Output Resistance	single-ended, (4)			50		Ω

(1) Typical values are stated for V_{CC} = +3.3V and T_A = +25°C.
(2) The total residual jitter at BER-12 was calculated as DJ+14.1xRJ, where DJ is deterministic jitter and RJ is random jitter. The jitter is expressed as a portion of a unit interval (UI). One UI is a reciprocal of a bit rate (or data rate). For example, a 1.5 Gbps (gigabit per second) signal has 1 / (1.5 Gb/s) = 666.67 ps (picosecond) unit interval. A 0.25 UI jitter is equivalent to 0.25 x 666.67 ps = 166.67 ps.
(3) Specification is ensured by characterization.
(4) Specification is ensured by design.

CONNECTION DIAGRAM



16-Pad WQFN
Package Number RGH0016A

PIN DESCRIPTIONS

Pin #	Name	Description
1	GND	Ground pin.
2	IN+	Non-inverting input pin.
3	IN-	Inverting input pin.
4	GND	Ground pin.
5	CAP+	Loop filter positive pin.
6	CAP-	Loop filter negative pin.
7	GND	Ground pin.
8	GND	Ground pin.
9	GND	Ground pin.
10	OUT-	Inverting output pin.
11	OUT+	Non-inverting output pin.
12	GND	Ground pin.
13	VCC	Power supply pin.
14	$\overline{EN}$	Output enable pin.
15	LOS	Los of signal circuitry output pin.
16	VCC	Power supply pin.

DEVICE OPERATION

Input Interfacing

The DS15EA101 accepts either differential or single-ended input. The input must be AC coupled. Transformer coupling is not supported. If the signal is differential, its amplitude must be 800 mVp-p ±10% (400 mV single-ended). If the signal is single-ended, its amplitude must be 800 mV ±10%.

Output Interfacing

The DS15EA101 uses current mode outputs. They are internally terminated with 50Ω. The following two figures illustrate typical DC-coupled interface to common differential receivers and assume that the receivers have high impedance inputs. While most receivers have an input common mode voltage range that can accomodate CML signals, it is recommended to check respective receiver's datasheet prior to implementing the suggested interface implementations.

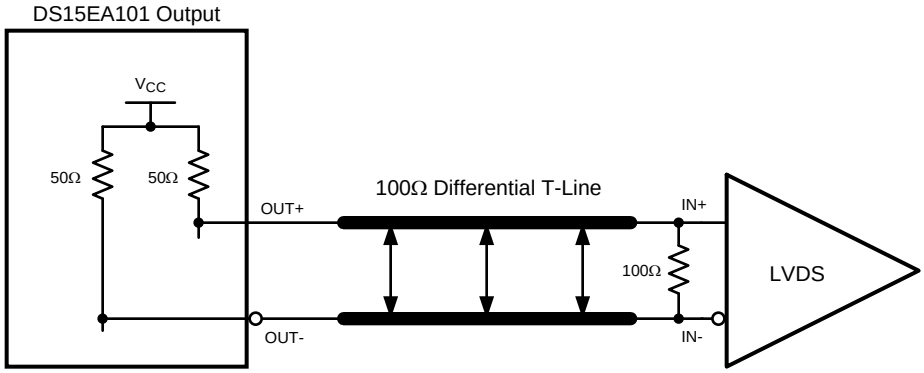


Figure 1. Typical DS15EA101 Output DC-Coupled Interface to an LVDS Receiver

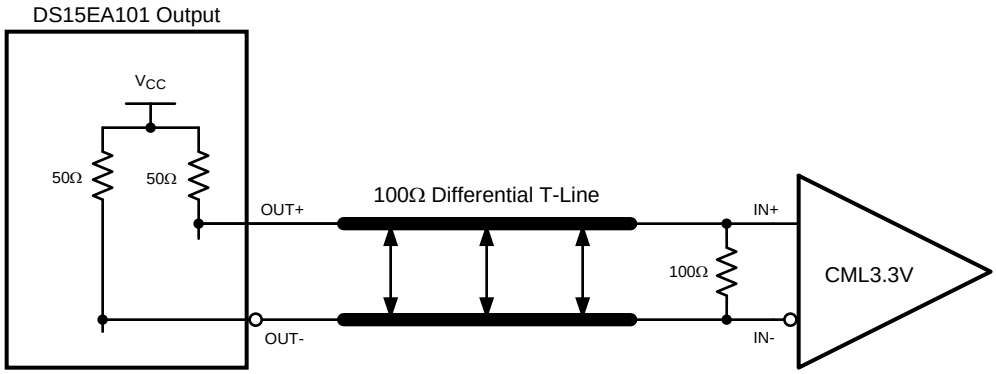


Figure 2. Typical DS15EA101 Output DC-Coupled Interface to a CML Receiver

Cable Extender Application

The DS15EA101 together with the DS15BA101 form a cable extender chipset optimized for extending serial data streams from serializer/deserializer (SerDes) pairs and field programmable gate arrays (FPGAs) over 100Ω differential (i.e. CAT5e/6/7 and twinax) and 50Ω coaxial cables. Setting correct DS15BA101 output amplitude and proper cable termination are keys for optimal operation. The following two figures show recommended chipset configuration for 100Ω differential and 50Ω coaxial cables.

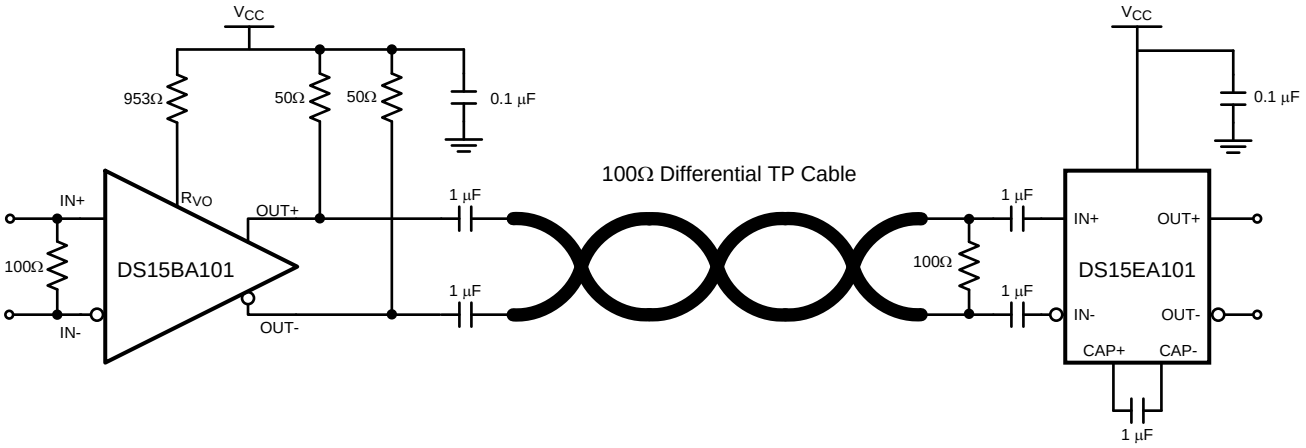


Figure 3. Cable Extender Chipset Connection Diagram for 100Ω Differential Cables

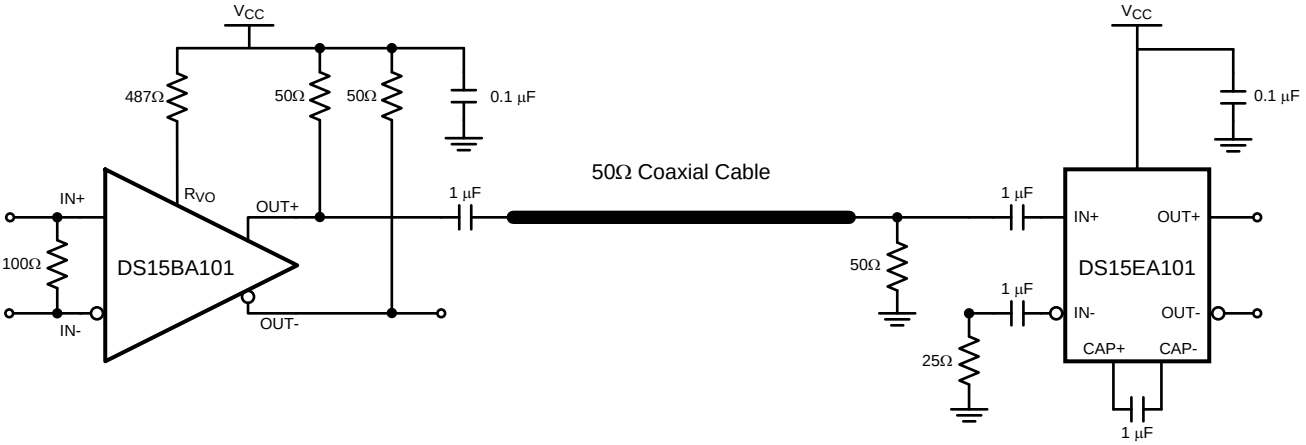


Figure 4. Cable Extender Chipset Connection Diagram for 50Ω Coaxial Cables

Reference Design

There is a complete reference design (P/N: DriveCable02EVK) available for evaluation of the cable extender chipset (DS15BA101 and DS15EA101).

For more information visit http://www.ti.com/tool/drivecable02evk

Typical Performance

Maximum Data Rate as a Function of CAT7 (Siemon CAT7 Tera) Length

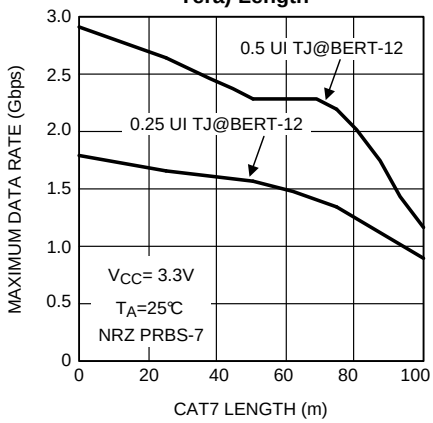


Figure 5.

Maximum Data Rate as a Function of CAT5e (Belden 1700A) Length

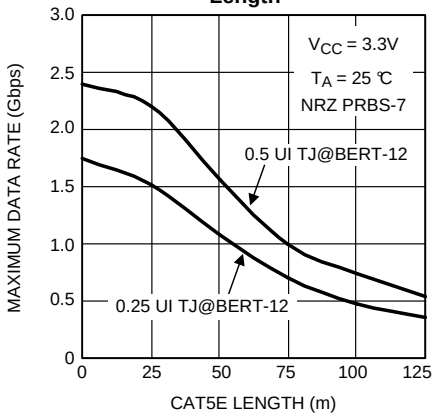


Figure 6.

Maximum Data Rate as a Function of 50Ω Coaxial (Belden 9914) Length

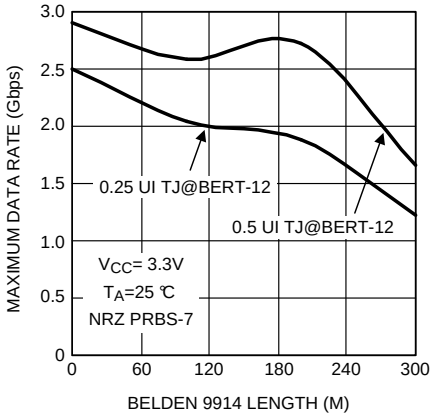


Figure 7.

Residual Jitter as a Function of Data Rate and Temperature for the Chipset with 50m CAT5e

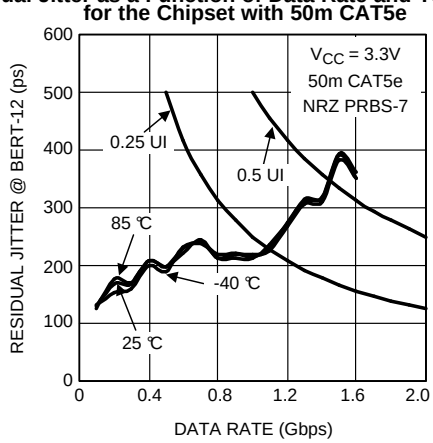


Figure 8.

Residual Jitter as a Function of Data Rate and Temperature for the Chipset with 75m CAT5e

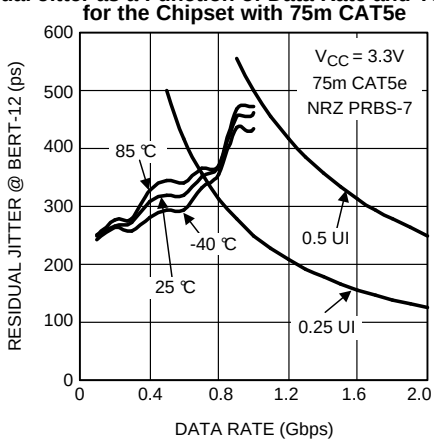


Figure 9.

Residual Jitter as a Function of Data Rate and Temperature for the Chipset with 100m CAT5e

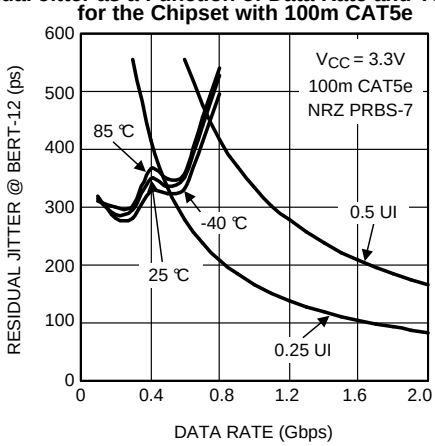


Figure 10.

Typical Performance (continued)

A 1.5 Gbps NRZ PRBS-7 After 25m CAT5e
V:100 mV / DIV, H:100 ps / DIV

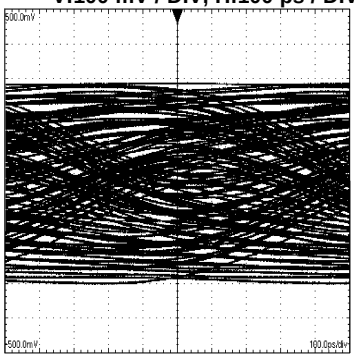


Figure 11.

An Equalized 1.5 Gbps NRZ PRBS-7 After 25m CAT5e
V:100 mV / DIV, H:100 ps / DIV

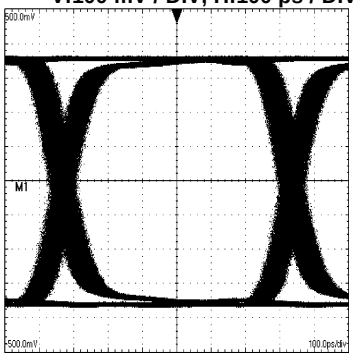


Figure 12.

A 1.0 Gbps NRZ PRBS-7 After 50m CAT5e
V:100 mV / DIV, H:150 ps / DIV

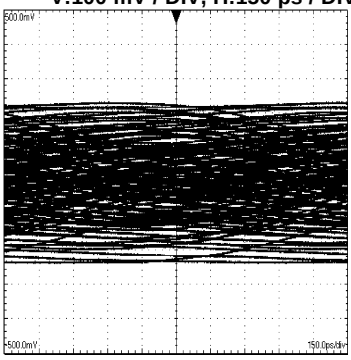


Figure 13.

An Equalized 1.0 Gbps NRZ PRBS-7 After 50m CAT5e
V:100 mV / DIV, H:150 ps / DIV

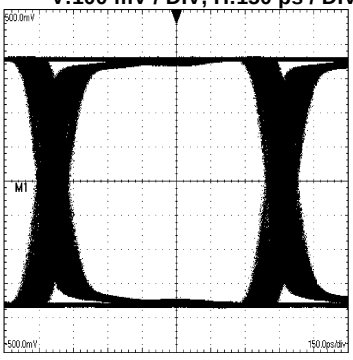


Figure 14.

A 0.5 Gbps NRZ PRBS-7 After 100m CAT5e
V:100 mV / DIV, H:400 ps / DIV

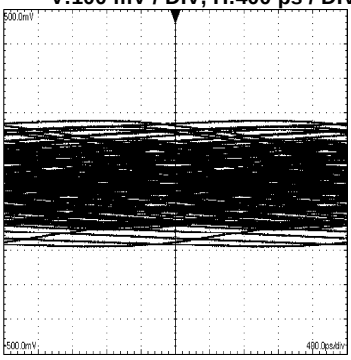


Figure 15.

An Equalized 0.5 Gbps NRZ PRBS-7 After 100m CAT5e
V:100 mV / DIV, H:400 ps / DIV

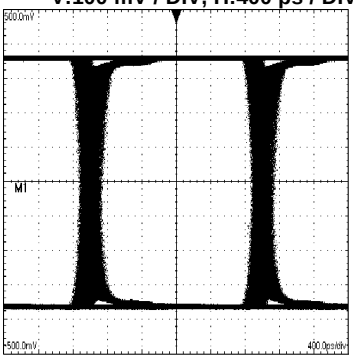


Figure 16.

Typical Performance (continued)

A 1.5 Gbps NRZ PRBS-7 After 50m CAT7
V:100 mV / DIV, H:100 ps / DIV

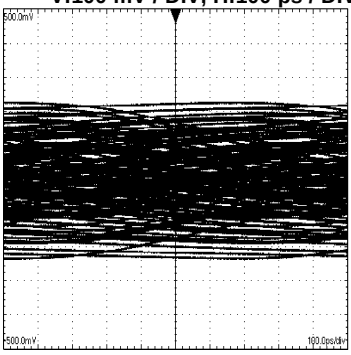


Figure 17.

An Equalized 1.5 Gbps NRZ PRBS-7 After 50m CAT7
V:100 mV / DIV, H:100 ps / DIV

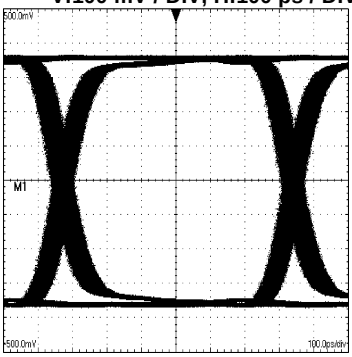


Figure 18.

An Equalized 1.5 Gbps NRZ PRBS-7 After 75m CAT7
V:100 mV / DIV, H:100 ps / DIV

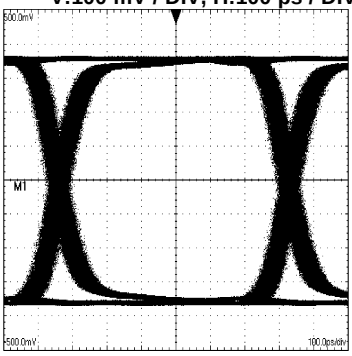


Figure 19.

A 1.5 Gbps NRZ PRBS-7 After 75m CAT7
V:100 mV / DIV, H:100 ps / DIV

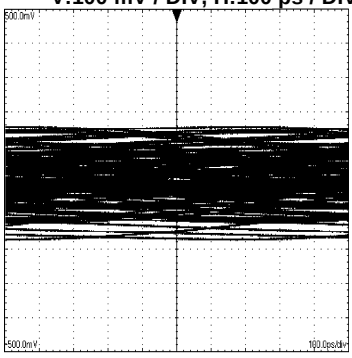


Figure 20.

A 1.0 Gbps NRZ PRBS-7 After 100m CAT7
V:100 mV / DIV, H:150 ps / DIV

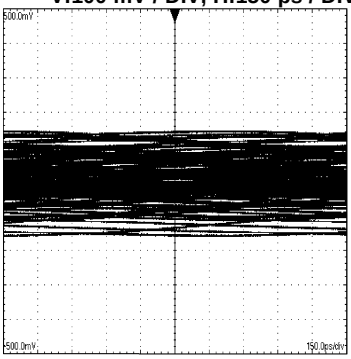


Figure 21.

An Equalized 1.0 Gbps NRZ PRBS-7 After 100m CAT7
V:100 mV / DIV, H:150 ps / DIV

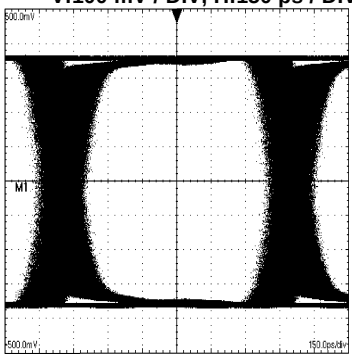


Figure 22.

Typical Performance (continued)

A 1.5 Gbps NRZ PRBS-7 After 200m Belden 9914 V:100 mV / DIV, H:100 ps / DIV

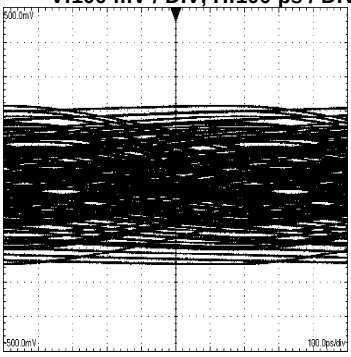


Figure 23.

An Equalized 1.5 Gbps NRZ PRBS-7 After 200m Belden 9914, V:100 mV / DIV, H:100 ps / DIV

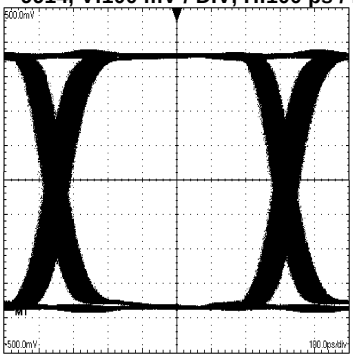


Figure 24.

REVISION HISTORY

Changes from Revision G (April 2013) to Revision H	Page
• Changed layout of National Data Sheet to TI format	10

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS15EA101SQ/NOPB	Active	Production	WQFN (RGH) | 16	1000 | SMALL T&R	Yes	SN	Level-3-260C-168 HR	-40 to 85	15EA101
DS15EA101SQ/NOPB.A	Active	Production	WQFN (RGH) | 16	1000 | SMALL T&R	Yes	SN	Level-3-260C-168 HR	-40 to 85	15EA101
DS15EA101SQE/NOPB	Active	Production	WQFN (RGH) | 16	250 | SMALL T&R	Yes	SN	Level-3-260C-168 HR	-40 to 85	15EA101
DS15EA101SQE/NOPB.A	Active	Production	WQFN (RGH) | 16	250 | SMALL T&R	Yes	SN	Level-3-260C-168 HR	-40 to 85	15EA101

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

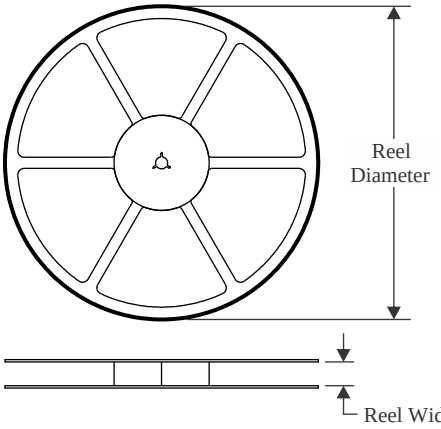
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

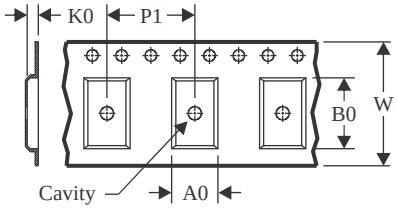
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

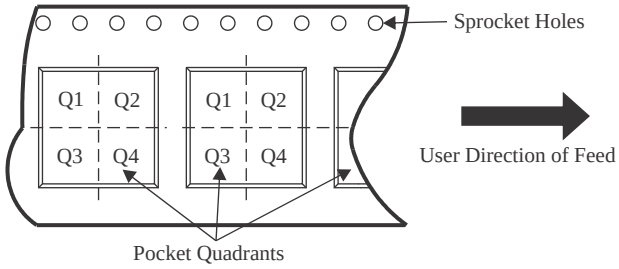


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

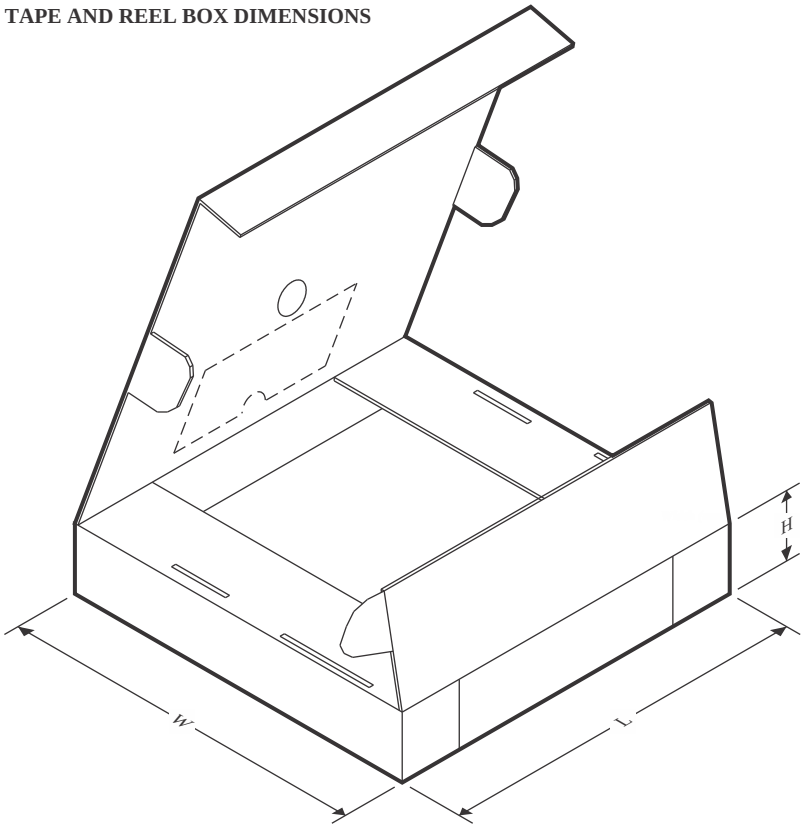
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS15EA101SQ/NOPB	WQFN	RGH	16	1000	177.8	12.4	4.3	4.3	1.3	8.0	12.0	Q1
DS15EA101SQE/NOPB	WQFN	RGH	16	250	177.8	12.4	4.3	4.3	1.3	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

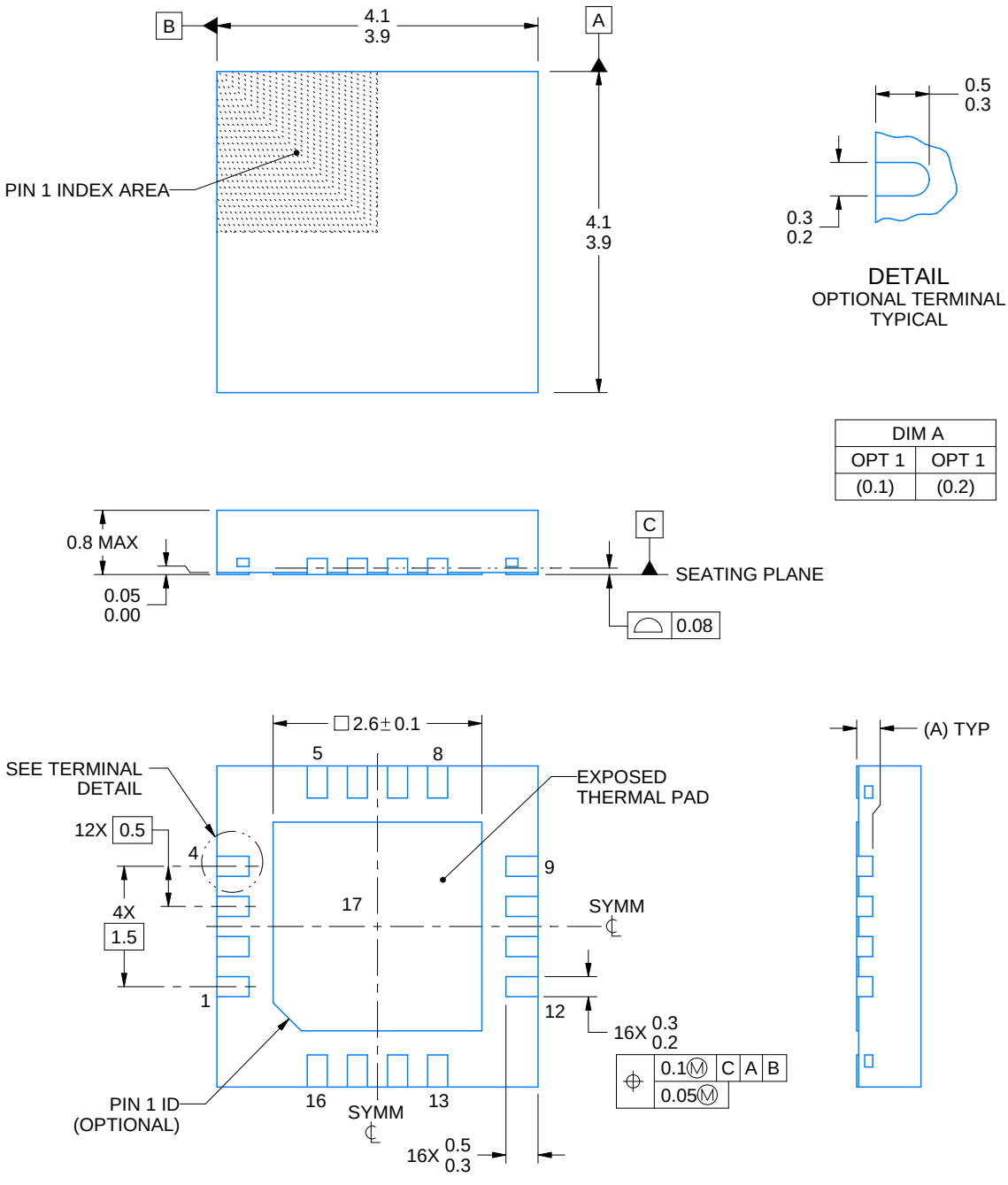
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS15EA101SQ/NOPB	WQFN	RGH	16	1000	208.0	191.0	35.0
DS15EA101SQE/NOPB	WQFN	RGH	16	250	208.0	191.0	35.0

PACKAGE OUTLINE

RGH0016A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

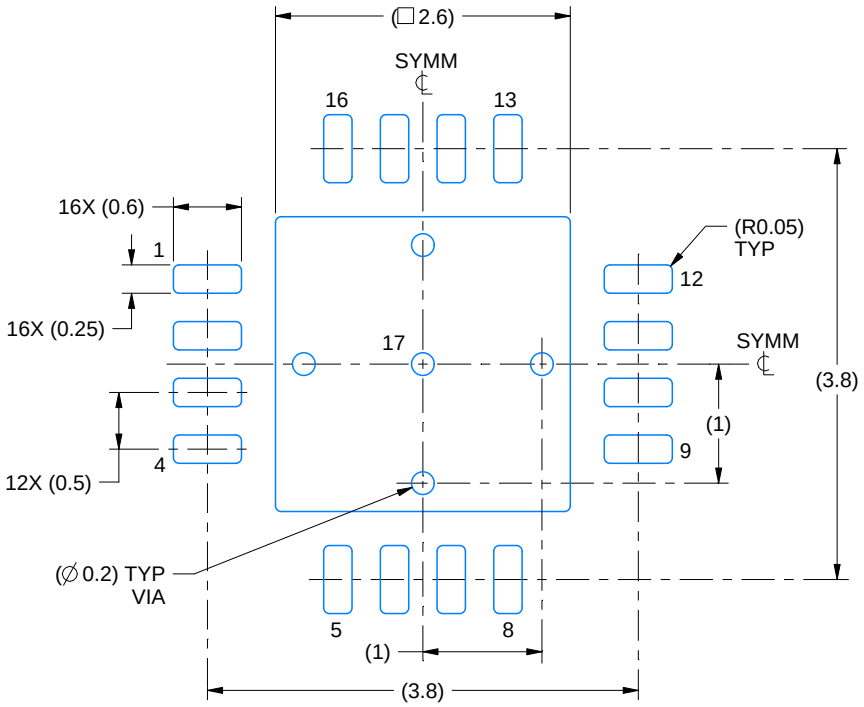
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

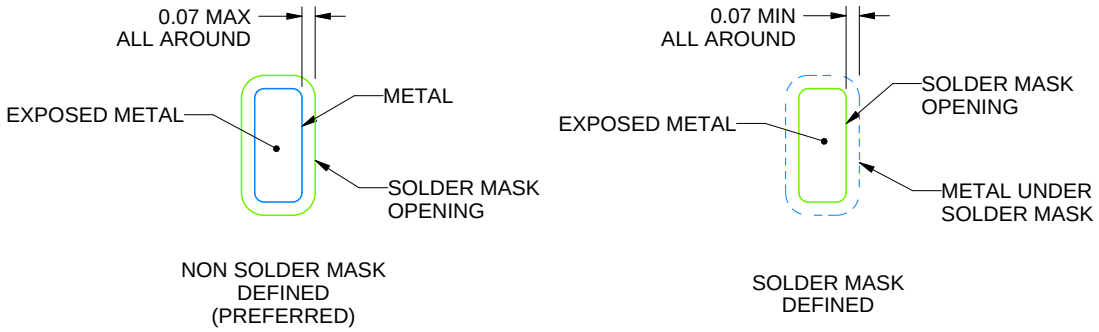
RGH0016A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

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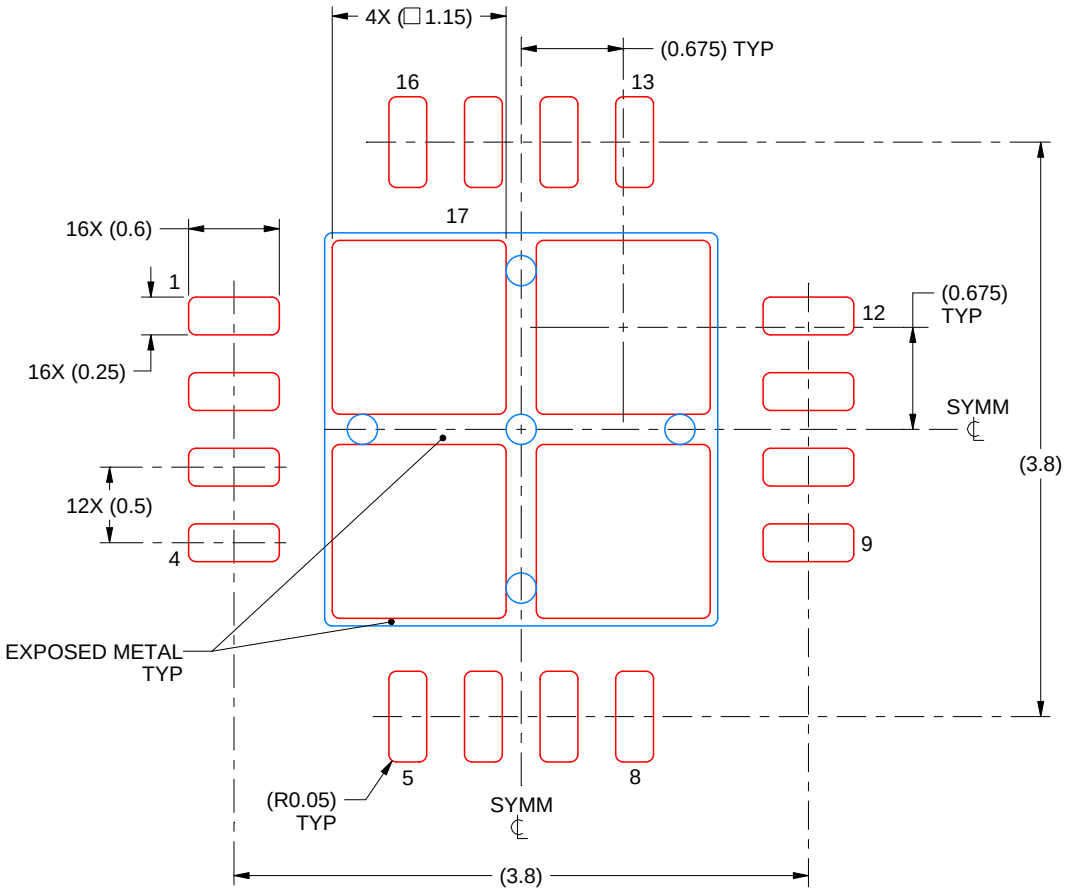
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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